

ABS22 THRU ABS210

SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIERS

Voltage Range - 200 to 1000 Volts Current - 2.0 Ampere



- Ideal for printed circuit board
 Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°C/10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability
- Glass passivated chip junction

MECHANICAL DATA

Case: Molded plastic body Terminals: Plated leads solderable per MIL-STD-750, Method 2026 Polarity: Polarity symbols marked on case Mounting Position: Any

Dimensions in inches and (millimeters)

ABS

0.028(0.7)

161(4.1)

0.200(5.1)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz resistive or inductive load, for capacitive load derate current by 20%.

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SYMBOLS	ABS22	ABS24	ABS26	ABS28	ABS210	UNITS
Vrrm	200	400	600	800	1000	VOLTS
Vrms	140	280	420	560	700	VOLTS
Vdc	200	400	600	800	1000	VOLTS
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IF(AV)	IF(AV) 2.0					Amps
IFSM	Ігѕм 60					Amps
Vr	1.1					Volts
VF						
1-	5.0 500					uA uA
IR						
R0jl 25						
Rθja	40					°C/W
TJ	-55 to +150					°C
Тѕтс	-55 to +150					°C
	VRRM VRMS VDC IF(AV) IFSM VF IR RθJL RθJA Tj	VRM 200 VRMS 140 Vbc 200 IF(AV) 200 IFSM 1 VF 1 IR R R 1 TJ 1	VRM 200 400 VRMS 140 280 VDc 200 400 IF(AV) 200 400 IF(AV) IF IF IFSM IF IF IR IR IR R0JL R0JA TJ	VRM 200 400 600 VRMS 140 280 420 VDC 200 400 600 IF(AV) 2.0 400 600 IF(AV) 2.0 400 600 IFSM 60 60 VF 1.1 60 R0JL 25 700 R0JA 40 40	VRM 200 400 600 800 VRMS 140 280 420 560 Vbc 200 400 600 800 Vbc 200 400 600 800 IF(AV) 2.0 2.0 60 800 IFSM 60 1.1 60 500 VF 1.1 1.1 1.1 1.1 IR 5.0 500 500 500 RθJL 225 40 40 40 TJ -55 to +150 500 500	VRM 200 400 600 800 1000 VRMS 140 280 420 560 700 Vbc 200 400 600 800 1000 Vbc 200 400 600 800 1000 IF(AV) 2:0 2:0 2:0 1000 IF(AV) 2:0 2:0 1:00 1:00 IF(AV) 2:0 5:0 5:0 5:0 IR 5:0 5:00 5:00 5:00 5:00 R0JL 2:5 40 40 40 1:1 TJ -55 to +150 5:0 5:0 5:0 5:0

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads

2.On ăluminum substrate P.C.B. with on area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad 3. Thermal resistance form junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

